

Features

- Wide Range of Digital and Analog Signal Levels
 - Digital 3V to 20V
 - Analog $\leq 20V_{P-P}$
- Low ON Resistance, 125 Ω (Typ) Over 15V_{P-P} Signal Input Range for $V_{DD}-V_{EE} = 18V$
- High OFF Resistance, Channel Leakage of $\pm 100pA$ (Typ) at $V_{DD}-V_{EE} = 18V$
- Logic-Level Conversion for Digital Addressing Signals of 3V to 20V ($V_{DD}-V_{SS} = 3V$ to 20V) to Switch Analog Signals to 20V_{P-P} ($V_{DD}-V_{EE} = 20V$)
- Matched Switch Characteristics, $r_{ON} = 5\Omega$ (Typ) for $V_{DD}-V_{EE} = 15V$
- Very Low Quiescent Power Dissipation Under All Digital-Control Input and Supply Conditions, 0.2 μW (Typ) at $V_{DD}-V_{SS} = V_{DD}-V_{EE} = 10V$
- Binary Address Decoding on Chip
- 5V, 10V, and 15V Parametric Ratings
- 100% Tested for Quiescent Current at 20V
- Maximum Input Current of 1 μA at 18V Over Full Package Temperature Range, 100nA at 18V and 25 $^{\circ}C$
- Break-Before-Make Switching Eliminates Channel Overlap

Applications

- Analog and Digital Multiplexing and Demultiplexing
- A/D and D/A Conversion
- Signal Gating

CMOS Analog Multiplexers/Demultiplexers with Logic Level Conversion

The CD4051B, CD4052B, and CD4053B analog multiplexers are digitally-controlled analog switches having low ON impedance and very low OFF leakage current. Control of analog signals up to 20V_{P-P} can be achieved by digital signal amplitudes of 4.5V to 20V (if $V_{DD}-V_{SS} = 3V$, a $V_{DD}-V_{EE}$ of up to 13V can be controlled; for $V_{DD}-V_{EE}$ level differences above 13V, a $V_{DD}-V_{SS}$ of at least 4.5V is required). For example, if $V_{DD} = +4.5V$, $V_{SS} = 0V$, and $V_{EE} = -13.5V$, analog signals from -13.5V to +4.5V can be controlled by digital inputs of 0V to 5V. These multiplexer circuits dissipate extremely low quiescent power over the full $V_{DD}-V_{SS}$ and $V_{DD}-V_{EE}$ supply-voltage ranges, independent of the logic state of the control signals. When a logic "1" is present at the inhibit input terminal, all channels are off.

The CD4051B is a single 8-Channel multiplexer having three binary control inputs, A, B, and C, and an inhibit input. The three binary signals select 1 of 8 channels to be turned on, and connect one of the 8 inputs to the output.

The CD4052B is a differential 4-Channel multiplexer having two binary control inputs, A and B, and an inhibit input. The two binary input signals select 1 of 4 pairs of channels to be turned on and connect the analog inputs to the outputs.

The CD4053B is a triple 2-Channel multiplexer having three separate digital control inputs, A, B, and C, and an inhibit input. Each control input selects one of a pair of channels which are connected in a single-pole, double-throw configuration.

When these devices are used as demultiplexers, the "CHANNEL IN/OUT" terminals are the outputs and the "COMMON OUT/IN" terminals are the inputs.

Ordering Information

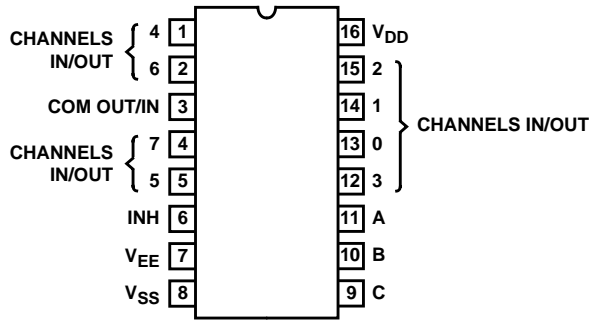
| PART NUMBER | TEMP. RANGE (°C) | PACKAGE |
|---|------------------|-------------------|
| CD4051BF3A, CD4052BF3A, CD4053BF3A | -55 to 125 | 16 Ld CERAMIC DIP |
| CD4051BE, CD4052BE, CD4053BE | -55 to 125 | 16 Ld PDIP |
| CD4051BM, CD4051BMT, CD4051BM96 CD4052BM, CD4052BMT, CD4052BM96 CD4053BM, CD4053BMT, CD4053BM96 | -55 to 125 | 16 Ld SOIC |
| CD4051BNSR, CD4052BNSR, CD4053BNSR | -55 to 125 | 16 Ld SOP |
| CD4051BPW, CD4051BPWR, CD4052BPW, CD4052BPWR, CD4053BPW, CD4053BPWR | -55 to 125 | 16 Ld TSSOP |

NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

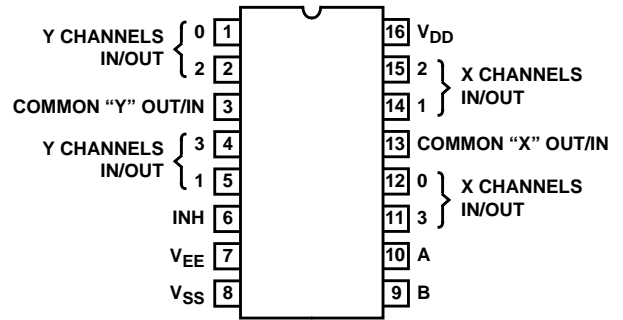
CD4051B, CD4052B, CD4053B

Pinouts

CD4051B (PDIP, CDIP, SOIC, SOP, TSSOP)
TOP VIEW



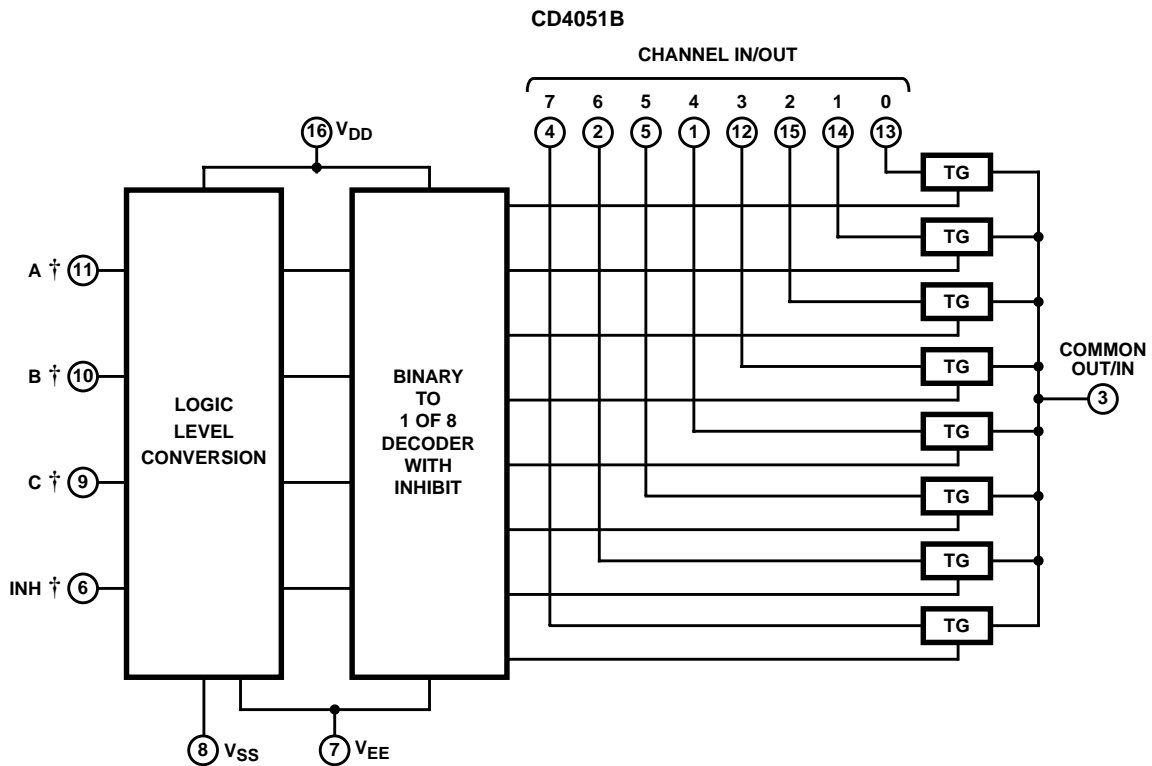
CD4052B (PDIP, CDIP, SOP, TSSOP)
TOP VIEW



CD4053B (PDIP, CDIP, SOP, TSSOP)
TOP VIEW



Functional Block Diagrams

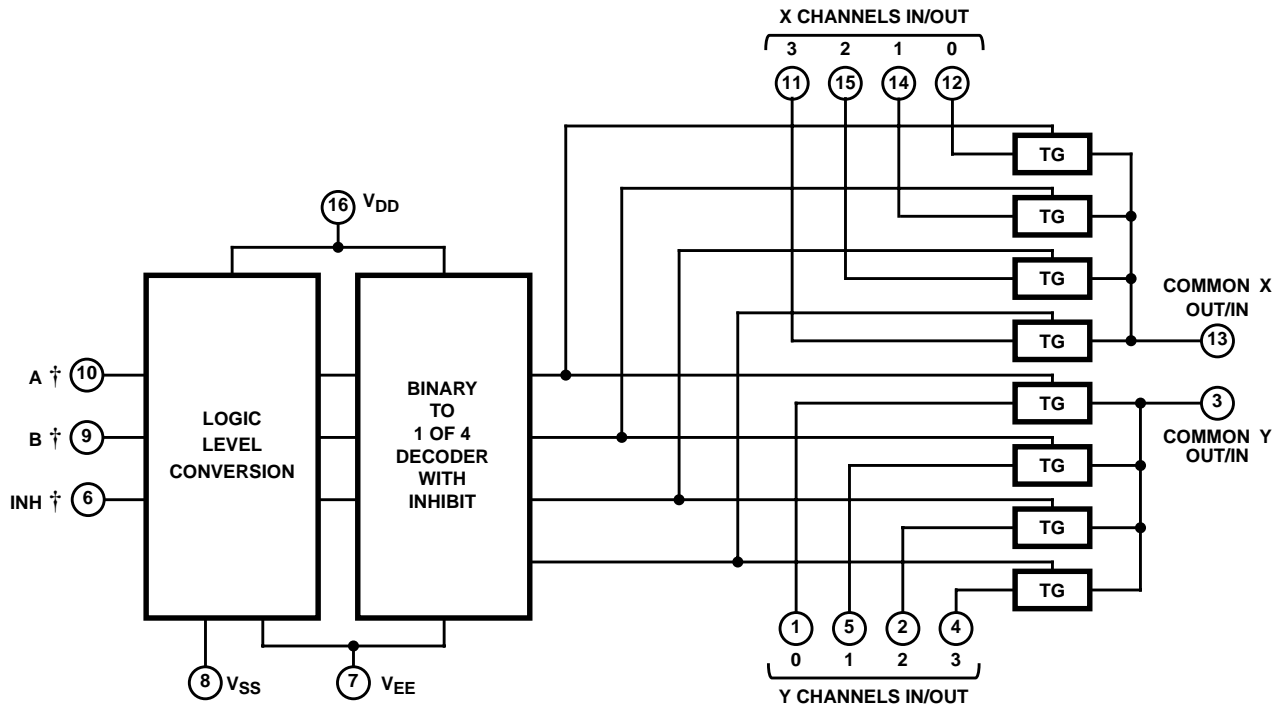


† All inputs are protected by standard CMOS protection network.

CD4051B, CD4052B, CD4053B

Functional Block Diagrams (Continued)

CD4052B



CD4053B



† All inputs are protected by standard CMOS protection network.

CD4051B, CD4052B, CD4053B

TRUTH TABLES

| INPUT STATES | | | | "ON" CHANNEL(S) |
|----------------|-------------|---|---|-----------------|
| INHIBIT | C | B | A | |
| CD4051B | | | | |
| 0 | 0 | 0 | 0 | 0 |
| 0 | 0 | 0 | 1 | 1 |
| 0 | 0 | 1 | 0 | 2 |
| 0 | 0 | 1 | 1 | 3 |
| 0 | 1 | 0 | 0 | 4 |
| 0 | 1 | 0 | 1 | 5 |
| 0 | 1 | 1 | 0 | 6 |
| 0 | 1 | 1 | 1 | 7 |
| 1 | X | X | X | None |
| CD4052B | | | | |
| INHIBIT | B | | A | |
| 0 | 0 | | 0 | 0x, 0y |
| 0 | 0 | | 1 | 1x, 1y |
| 0 | 1 | | 0 | 2x, 2y |
| 0 | 1 | | 1 | 3x, 3y |
| 1 | X | | X | None |
| CD4053B | | | | |
| INHIBIT | A OR B OR C | | | |
| 0 | 0 | | | ax or bx or cx |
| 0 | 1 | | | ay or by or cy |
| 1 | X | | | None |

X = Don't Care

CD4051B, CD4052B, CD4053B

Absolute Maximum Ratings

Supply Voltage (V+ to V-)

Voltages Referenced to V_{SS} Terminal -0.5V to 20V
 DC Input Voltage Range -0.5V to V_{DD} +0.5V
 DC Input Current, Any One Input. ±10mA

Operating Conditions

Temperature Range -55°C to 125°C

Thermal Information

Package Thermal Impedance, θ_{JA} (see Note 1):

E (PDIP) package. 67°C/W
 M (SOIC) package 73°C/W
 NS (SOP) package. 64°C/W
 PW (TSSOP) package 108°C/W
 Maximum Junction Temperature (Ceramic Package) 175°C
 Maximum Junction Temperature (Plastic Package) 150°C
 Maximum Storage Temperature Range. -65°C to 150°C
 Maximum Lead Temperature (Soldering 10s) 265°C
 (SOIC - Lead Tips Only)


CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

- The package thermal impedance is calculated in accordance with JESD 51-7.

Electrical Specifications

Common Conditions Here: If Whole Table is For the Full Temp. Range, V_{SUPPLY} = ±5V, A_V = +1, R_L = 100Ω, Unless Otherwise Specified (Note 3)

| PARAMETER | CONDITIONS | | | | LIMITS AT INDICATED TEMPERATURES (°C) | | | | | | | UNITS | | |
|--|---|---|---------------------|---------------------|---------------------------------------|-----|----------------|------|-----|-------|---------------|-------|---|----|
| | V _{IS} (V) | V _{EE} (V) | V _{SS} (V) | V _{DD} (V) | -55 | -40 | 85 | 125 | 25 | | | | | |
| | | | | | | | | | MIN | TYP | MAX | | | |
| SIGNAL INPUTS (V_{IS}) AND OUTPUTS (V_{OS}) | | | | | | | | | | | | | | |
| Quiescent Device Current, I _{DD} Max | - | - | - | 5 | 5 | 5 | 150 | 150 | - | 0.04 | 5 | μA | | |
| | - | - | - | 10 | 10 | 10 | 300 | 300 | - | 0.04 | 10 | μA | | |
| | - | - | - | 15 | 20 | 20 | 600 | 600 | - | 0.04 | 20 | μA | | |
| | - | - | - | 20 | 100 | 100 | 3000 | 3000 | - | 0.08 | 100 | μA | | |
| Drain to Source ON Resistance r _{ON} Max 0 ≤ V _{IS} ≤ V _{DD} | - | 0 | 0 | 5 | 800 | 850 | 1200 | 1300 | - | 470 | 1050 | Ω | | |
| | - | 0 | 0 | 10 | 310 | 330 | 520 | 550 | - | 180 | 400 | Ω | | |
| | - | 0 | 0 | 15 | 200 | 210 | 300 | 320 | - | 125 | 240 | Ω | | |
| Change in ON Resistance (Between Any Two Channels), Δr _{ON} | - | 0 | 0 | 5 | - | - | - | - | - | 15 | - | Ω | | |
| | - | 0 | 0 | 10 | - | - | - | - | - | 10 | - | Ω | | |
| | - | 0 | 0 | 15 | - | - | - | - | - | 5 | - | Ω | | |
| OFF Channel Leakage Current: Any Channel OFF (Max) or ALL Channels OFF (Common OUT/IN) (Max) | - | 0 | 0 | 18 | ±100 (Note 2) | | ±1000 (Note 2) | | - | ±0.01 | ±100 (Note 2) | nA | | |
| Capacitance: | - | -5 | 5- | 5 | | | | | | | | | | |
| Input, C _{IS} | | | | | - | - | - | - | - | - | - | 5 | - | pF |
| Output, C _{OS} | | | | | | | | | | | | | | |
| CD4051 | | | | | - | - | - | - | - | - | - | 30 | - | pF |
| CD4052 | | | | | - | - | - | - | - | - | - | 18 | - | pF |
| CD4053 | - | - | - | - | - | - | - | 9 | - | pF | | | | |
| Feedthrough C _{IOS} | | | | | | | | | | | | | | |
| | - | - | - | - | - | - | - | - | - | 0.2 | - | pF | | |
| Propagation Delay Time (Signal Input to Output) |  | R _L = 200kΩ, C _L = 50pF, t _r , t _f = 20ns | 5 | - | - | - | - | - | - | 30 | 60 | ns | | |
| | | | 10 | - | - | - | - | - | - | 15 | 30 | ns | | |
| | | | 15 | - | - | - | - | - | - | 10 | 20 | ns | | |

CD4051B, CD4052B, CD4053B

Electrical Specifications Common Conditions Here: If Whole Table is For the Full Temp. Range, $V_{SUPPLY} = \pm 5V$, $A_V = +1$, $R_L = 100\Omega$, Unless Otherwise Specified **(Continued)** (Note 3)

| PARAMETER | CONDITIONS | | | | LIMITS AT INDICATED TEMPERATURES (°C) | | | | | | | UNITS |
|---|--|--|--------------|--------------|---------------------------------------|-----------|---------|---------|-----|---------------|-----------|---------|
| | V_{IS} (V) | V_{EE} (V) | V_{SS} (V) | V_{DD} (V) | -55 | -40 | 85 | 125 | 25 | | | |
| | | | | | | | | | MIN | TYP | MAX | |
| CONTROL (ADDRESS OR INHIBIT), V_C | | | | | | | | | | | | |
| Input Low Voltage, V_{IL} , Max | $V_{IL} = V_{DD}$ through 1k Ω ; $V_{IH} = V_{DD}$ through 1k Ω | $V_{EE} = V_{SS}$, $R_L = 1k\Omega$ to V_{SS} , $I_{IS} < 2\mu A$ on All OFF Channels | 5 | 1.5 | 1.5 | 1.5 | 1.5 | - | - | 1.5 | V | |
| | | | 10 | 3 | 3 | 3 | 3 | - | - | 3 | V | |
| | | | 15 | 4 | 4 | 4 | 4 | - | - | 4 | V | |
| Input High Voltage, V_{IH} , Min | $V_{IL} = V_{DD}$ through 1k Ω ; $V_{IH} = V_{DD}$ through 1k Ω | $V_{EE} = V_{SS}$, $R_L = 1k\Omega$ to V_{SS} , $I_{IS} < 2\mu A$ on All OFF Channels | 5 | 3.5 | 3.5 | 3.5 | 3.5 | 3.5 | - | - | V | |
| | | | 10 | 7 | 7 | 7 | 7 | 7 | - | - | V | |
| | | | 15 | 11 | 11 | 11 | 11 | 11 | - | - | V | |
| Input Current, I_{IN} (Max) | $V_{IN} = 0, 18$ | | | 18 | ± 0.1 | ± 0.1 | ± 1 | ± 1 | - | $\pm 10^{-5}$ | ± 0.1 | μA |
| Propagation Delay Time: Address-to-Signal OUT (Channels ON or OFF) See Figures 10, 11, 14 | $t_r, t_f = 20ns$, $C_L = 50pF$, $R_L = 10k\Omega$ | 0 | 0 | 5 | - | - | - | - | - | 450 | 720 | ns |
| | | 0 | 0 | 10 | - | - | - | - | - | 160 | 320 | ns |
| | | 0 | 0 | 15 | - | - | - | - | - | 120 | 240 | ns |
| | | -5 | 0 | 5 | - | - | - | - | - | 225 | 450 | ns |
| Propagation Delay Time: Inhibit-to-Signal OUT (Channel Turning ON) See Figure 11 | $t_r, t_f = 20ns$, $C_L = 50pF$, $R_L = 1k\Omega$ | 0 | 0 | 5 | - | - | - | - | - | 400 | 720 | ns |
| | | 0 | 0 | 10 | - | - | - | - | - | 160 | 320 | ns |
| | | 0 | 0 | 15 | - | - | - | - | - | 120 | 240 | ns |
| | | -10 | 0 | 5 | - | - | - | - | - | 200 | 400 | ns |
| Propagation Delay Time: Inhibit-to-Signal OUT (Channel Turning OFF) See Figure 15 | $t_r, t_f = 20ns$, $C_L = 50pF$, $R_L = 10k\Omega$ | 0 | 0 | 5 | - | - | - | - | - | 200 | 450 | ns |
| | | 0 | 0 | 10 | - | - | - | - | - | 90 | 210 | ns |
| | | 0 | 0 | 15 | - | - | - | - | - | 70 | 160 | ns |
| | | -10 | 0 | 5 | - | - | - | - | - | 130 | 300 | ns |
| Input Capacitance, C_{IN} (Any Address or Inhibit Input) | | | | | - | - | - | - | - | 5 | 7.5 | pF |

NOTE:

- Determined by minimum feasible leakage measurement for automatic testing.

Electrical Specifications

| PARAMETER | TEST CONDITIONS | | | LIMITS | | UNITS | |
|--|-----------------|--------------|---------------------|---|-------------------------|-------|-----|
| | V_{IS} (V) | V_{DD} (V) | R_L (k Ω) | TYP | | | |
| Cutoff (-3dB) Frequency Channel ON (Sine Wave Input) | 5 (Note 3) | 10 | 1 | V_{OS} at Common OUT/IN | CD4053 | 30 | MHz |
| | | | | | CD4052 | 25 | MHz |
| | | | | | CD4051 | 20 | MHz |
| | | | | $V_{EE} = V_{SS}$, $20\text{Log} \frac{V_{OS}}{V_{IS}} = -3\text{dB}$ | V_{OS} at Any Channel | 60 | MHz |

Electrical Specifications

| PARAMETER | TEST CONDITIONS | | | LIMITS | | | |
|--|---|---------------------|---------------------|---------------------------------------|-------------------------|--------|--------------------|
| | V _{IS} (V) | V _{DD} (V) | R _L (kΩ) | TYP | UNITS | | |
| Total Harmonic Distortion, THD | 2 (Note 3) | 5 | 10 | 0.3 | % | | |
| | 3 (Note 3) | 10 | | 0.2 | % | | |
| | 5 (Note 3) | 15 | | 0.12 | % | | |
| | V _{EE} = V _{SS} , f _{IS} = 1kHz Sine Wave | | | | % | | |
| -40dB Feedthrough Frequency (All Channels OFF) | 5 (Note 3) | 10 | 1 | V _{OS} at Common OUT/IN | CD4053 | 8 | MHz |
| | V _{EE} = V _{SS} , 20Log $\frac{V_{OS}}{V_{IS}} = -40\text{dB}$ | | | | | CD4052 | 10 |
| | | | | | | CD4051 | 12 |
| | | | | V _{OS} at Any Channel | | 8 | MHz |
| -40dB Signal Crosstalk Frequency | 5 (Note 3) | 10 | 1 | Between Any 2 Channels | | 3 | MHz |
| | V _{EE} = V _{SS} , 20Log $\frac{V_{OS}}{V_{IS}} = -40\text{dB}$ | | | Between Sections, CD4052 Only | Measured on Common | 6 | MHz |
| | | | | | Measured on Any Channel | 10 | MHz |
| | | | | Between Any Two Sections, CD4053 Only | In Pin 2, Out Pin 14 | 2.5 | MHz |
| | | | | | In Pin 15, Out Pin 14 | 6 | MHz |
| Address-or-Inhibit-to-Signal Crosstalk | - | 10 | 10 (Note 4) | | | 65 | mV _{PEAK} |
| | V _{EE} = 0, V _{SS} = 0, t _r , t _f = 20ns, V _{CC} = V _{DD} - V _{SS} (Square Wave) | | | | | 65 | mV _{PEAK} |

NOTES:

- Peak-to-Peak voltage symmetrical about $\frac{V_{DD} - V_{EE}}{2}$
- Both ends of channel.

Typical Performance Curves



FIGURE 1. CHANNEL ON RESISTANCE vs INPUT SIGNAL VOLTAGE (ALL TYPES)



FIGURE 2. CHANNEL ON RESISTANCE vs INPUT SIGNAL VOLTAGE (ALL TYPES)

Typical Performance Curves (Continued)

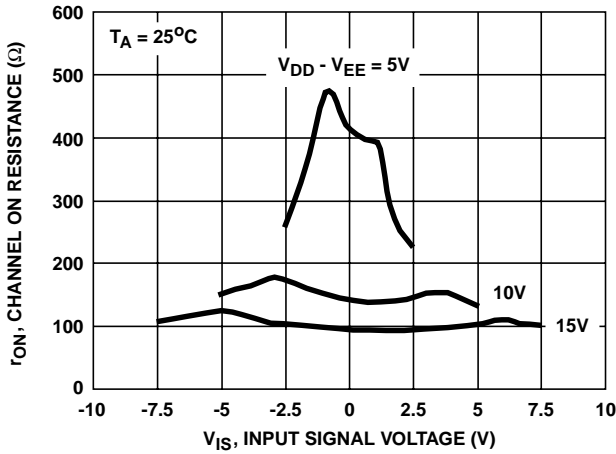


FIGURE 3. CHANNEL ON RESISTANCE vs INPUT SIGNAL VOLTAGE (ALL TYPES)



FIGURE 4. CHANNEL ON RESISTANCE vs INPUT SIGNAL VOLTAGE (ALL TYPES)

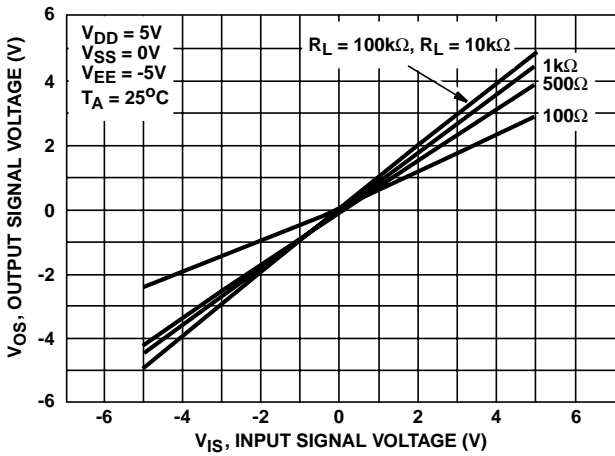


FIGURE 5. ON CHARACTERISTICS FOR 1 OF 8 CHANNELS (CD4051B)



FIGURE 6. DYNAMIC POWER DISSIPATION vs SWITCHING FREQUENCY (CD4051B)



FIGURE 7. DYNAMIC POWER DISSIPATION vs SWITCHING FREQUENCY (CD4052B)

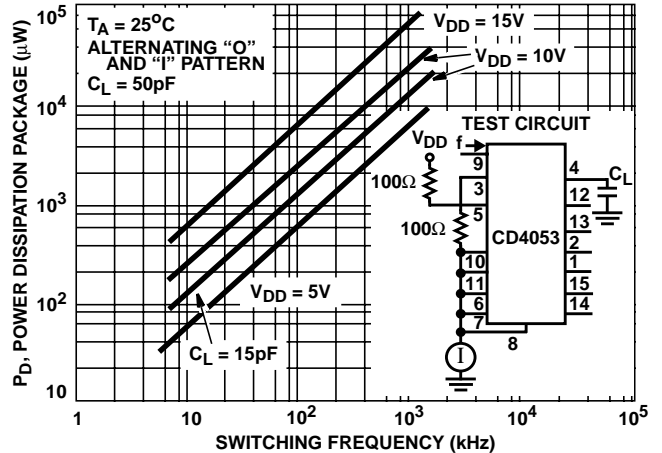


FIGURE 8. DYNAMIC POWER DISSIPATION vs SWITCHING FREQUENCY (CD4053B)

Test Circuits and Waveforms



NOTE: The ADDRESS (digital-control inputs) and INHIBIT logic levels are: "0" = V_{SS} and "1" = V_{DD} . The analog signal (through the TG) may swing from V_{EE} to V_{DD} .

FIGURE 9. TYPICAL BIAS VOLTAGES



FIGURE 10. WAVEFORMS, CHANNEL BEING TURNED ON ($R_L = 1k\Omega$)



FIGURE 11. WAVEFORMS, CHANNEL BEING TURNED OFF ($R_L = 1k\Omega$)



FIGURE 12. OFF CHANNEL LEAKAGE CURRENT - ANY CHANNEL OFF

Test Circuits and Waveforms (Continued)



FIGURE 13. OFF CHANNEL LEAKAGE CURRENT - ALL CHANNELS OFF

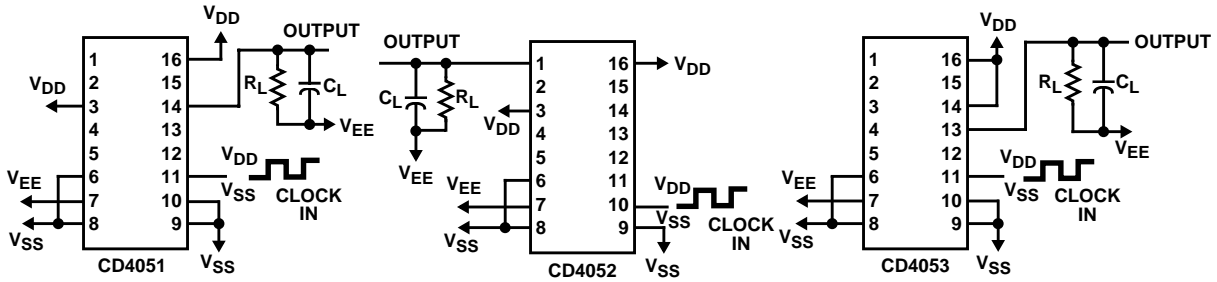


FIGURE 14. PROPAGATION DELAY - ADDRESS INPUT TO SIGNAL OUTPUT

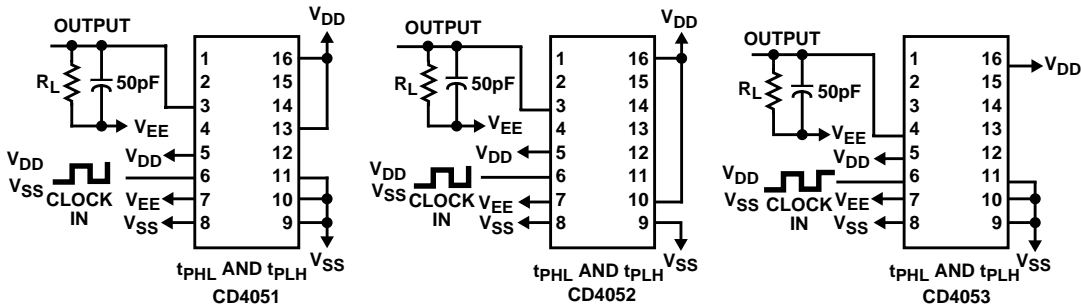
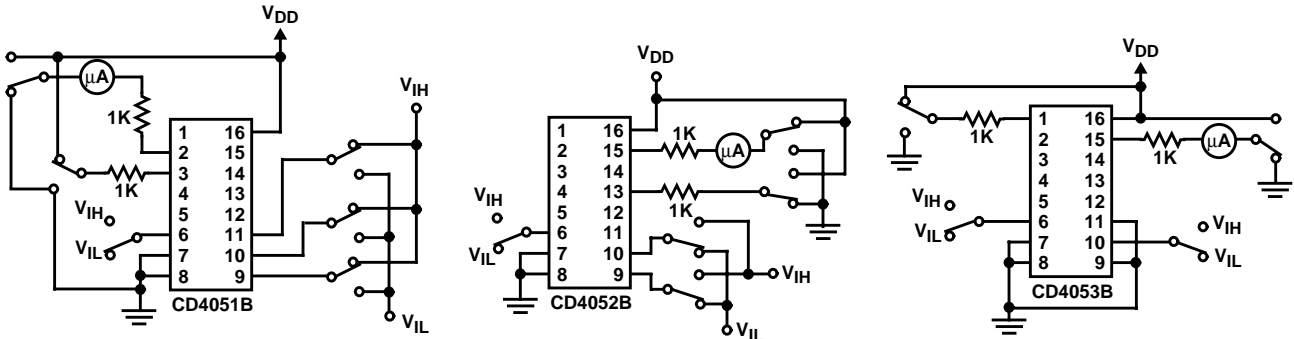


FIGURE 15. PROPAGATION DELAY - INHIBIT INPUT TO SIGNAL OUTPUT



MEASURE $< 2\mu\text{A}$ ON ALL "OFF" CHANNELS (e.g., CHANNEL 6)

MEASURE $< 2\mu\text{A}$ ON ALL "OFF" CHANNELS (e.g., CHANNEL 2x)

MEASURE $< 2\mu\text{A}$ ON ALL "OFF" CHANNELS (e.g., CHANNEL by)

FIGURE 16. INPUT VOLTAGE TEST CIRCUITS (NOISE IMMUNITY)

Test Circuits and Waveforms (Continued)



FIGURE 17. QUIESCENT DEVICE CURRENT



FIGURE 18. CHANNEL ON RESISTANCE MEASUREMENT CIRCUIT



FIGURE 19. INPUT CURRENT



FIGURE 20. FEEDTHROUGH (ALL TYPES)

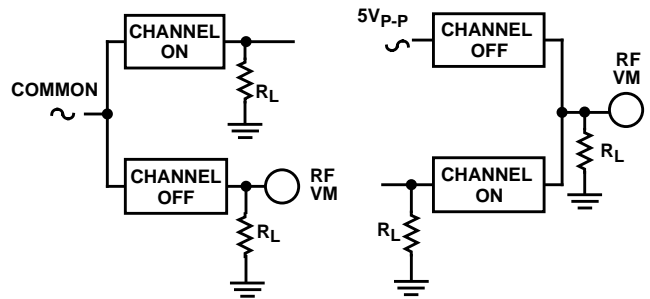


FIGURE 21. CROSSTALK BETWEEN ANY TWO CHANNELS (ALL TYPES)

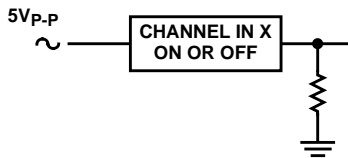


FIGURE 22. CROSSTALK BETWEEN DUALS OR TRIPLETS (CD4052B, CD4053B)

Test Circuits and Waveforms (Continued)



FIGURE 23. TYPICAL TIME-DIVISION APPLICATION OF THE CD4052B

Special Considerations

In applications where separate power sources are used to drive V_{DD} and the signal inputs, the V_{DD} current capability should exceed V_{DD}/R_L ($R_L =$ effective external load). This provision avoids permanent current flow or clamp action on the V_{DD} supply when power is applied or removed from the CD4051B, CD4052B or CD4053B.



FIGURE 24. 24-TO-1 MUX ADDRESSING

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| 7901502EA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| 8101801EA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| CD4051BE | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD4051BEE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD4051BF | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| CD4051BF3A | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| CD4051BF3AS2283 | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI |
| CD4051BM | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BM96 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BM96E4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BM96G3 | PREVIEW | SOIC | D | 16 | 2500 | TBD | Call TI | Call TI |
| CD4051BM96G4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BME4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BMG4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BMT | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BMTE4 | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BMTG4 | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BNSR | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BNSRE4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BNSRG4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BPW | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BPWE4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BPWG4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BPWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BPWRE4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4051BPWRG4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BE | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| CD4052BEE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD4052BF | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| CD4052BF3A | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| CD4052BM | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BM96 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BM96E4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BM96G3 | PREVIEW | SOIC | D | 16 | 2500 | TBD | Call TI | Call TI |
| CD4052BM96G4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BME4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BMG4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BMT | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BMTE4 | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BMTG4 | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BNSR | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BNSRE4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BNSRG4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BPW | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BPWE4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BPWG4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BPWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BPWRE4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4052BPWRG3 | PREVIEW | TSSOP | PW | 16 | 2000 | TBD | Call TI | Call TI |
| CD4052BPWRG4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BE | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD4053BEE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD4053BF | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| CD4053BF3A | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 | N / A for Pkg Type |
| CD4053BF3AS2283 | OBSOLETE | CDIP | J | 16 | | TBD | Call TI | Call TI |
| CD4053BM | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| | | | | | | no Sb/Br) | | |
| CD4053BM96 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BM96E4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BM96G3 | PREVIEW | SOIC | D | 16 | 2500 | TBD | Call TI | Call TI |
| CD4053BM96G4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BME4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BMG4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BMT | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BMTE4 | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BMTG4 | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BNSR | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BNSRE4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BNSRG4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BPW | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BPWE4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BPWG4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BPWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BPWRE4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD4053BPWRG3 | PREVIEW | TSSOP | PW | 16 | 2000 | TBD | Call TI | Call TI |
| CD4053BPWRG4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS

compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF CD4051B, CD4051B-MIL, CD4052B, CD4052B-MIL, CD4053B, CD4053B-MIL :

● Automotive: [CD4051B-Q1](#), [CD4053B-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD4051BM96 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4051BM96 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4051BNSR | SO | NS | 16 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| CD4051BPWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| CD4052BM96 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4052BNSR | SO | NS | 16 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| CD4052BPWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| CD4053BM96 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4053BNSR | SO | NS | 16 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| CD4053BPWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD4051BM96 | SOIC | D | 16 | 2500 | 346.0 | 346.0 | 33.0 |
| CD4051BM96 | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |
| CD4051BNSR | SO | NS | 16 | 2000 | 346.0 | 346.0 | 33.0 |
| CD4051BPWR | TSSOP | PW | 16 | 2000 | 346.0 | 346.0 | 29.0 |
| CD4052BM96 | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |
| CD4052BNSR | SO | NS | 16 | 2000 | 346.0 | 346.0 | 33.0 |
| CD4052BPWR | TSSOP | PW | 16 | 2000 | 346.0 | 346.0 | 29.0 |
| CD4053BM96 | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |
| CD4053BNSR | SO | NS | 16 | 2000 | 346.0 | 346.0 | 33.0 |
| CD4053BPWR | TSSOP | PW | 16 | 2000 | 346.0 | 346.0 | 29.0 |

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

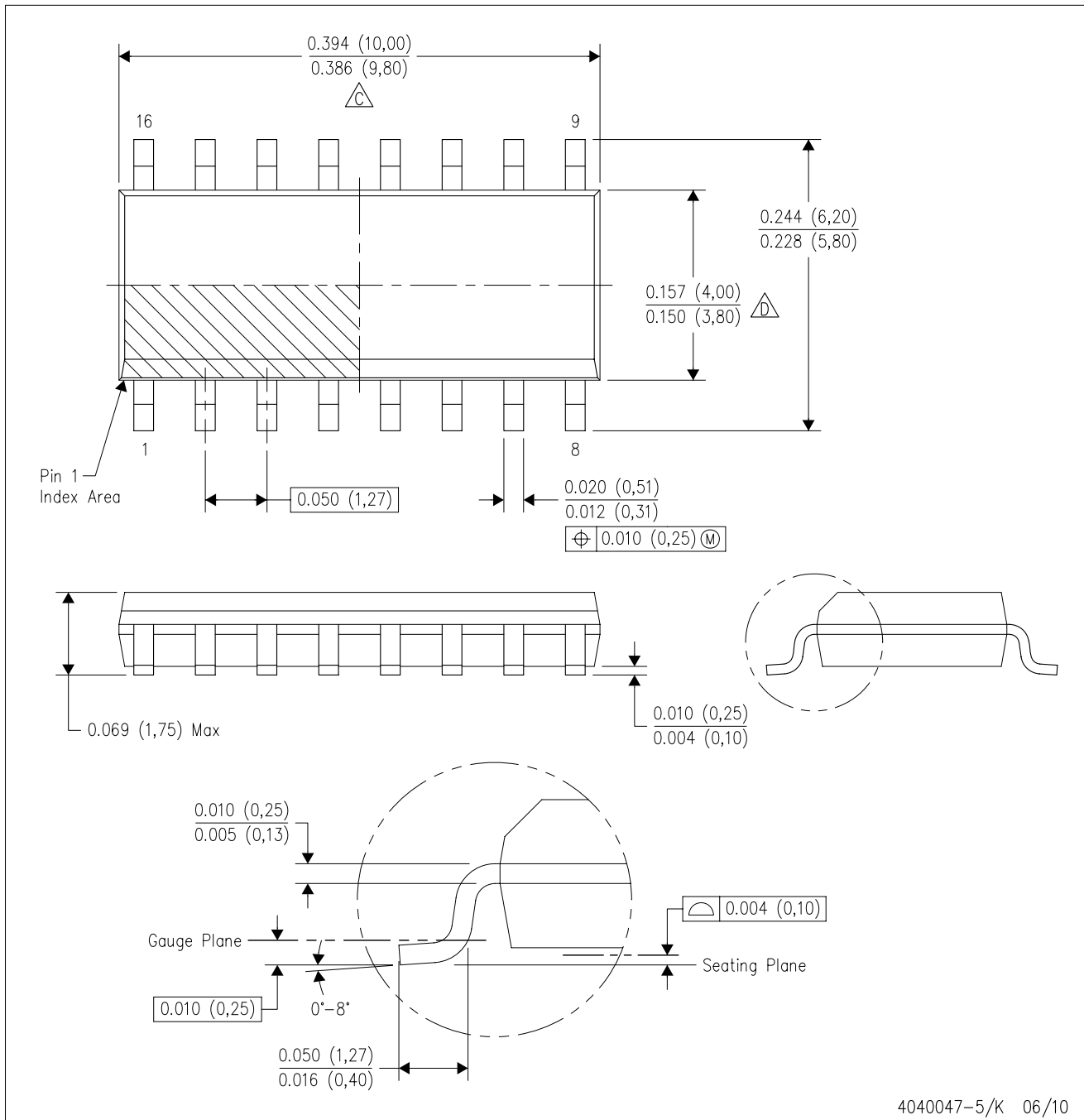
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AC.

D(R-PDSO-G16)



4209373/A 03/08

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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